

**PRINTED WIRING BOARD, ITS MANUFACTURING METHOD  
AND CIRCUIT DEVICE**

**ABSTRACT**

-- [Solution means] A process for producing a printed wiring board comprises the steps of depositing a base metal on at least one surface of an insulating film to form a base metal layer and further depositing copper or a copper alloy to form a conductive metal layer, then removing a surface metal layer, which is formed through the above step, by etching to form a wiring pattern, and then treating the base metal layer with a treating liquid capable of dissolving and/or passivating the metal that forms the base metal layer. The printed wiring board so provided comprises an insulating film and a wiring pattern formed on at least one surface of the insulating film, the wiring pattern including a base metal layer deposited on the insulating film surface and a conductive metal layer, the base metal layer for forming the wiring pattern protrudes in a widthwise direction more than the conductive metal layer for forming the wiring pattern. --